HP-150 Laboratory Hotplate

English selection sheet | Prepared from public manufacturer specifications



A Swiss standalone laboratory hotplate for photoresist soft bake and hard bake on wafers up to 150 mm. Substrate handling and vacuum fixation are manual.

Select the baking temperature and duration for the resist and substrate. Provide thickness, warpage, backside condition and the intended acceptance measurement method.

Model and configuration

Maximum wafer diameter	150 mm (6 inches)
Maximum substrate thickness	5 mm
Temperature range	Ambient to 250 degrees C
Temperature accuracy	+/-1 degree C at 100 degrees C
Handling and surface	Manual loading and vacuum fixation; safety-glass cover
Installation and options	Bench-top or bench-mounted; manual nitrogen flushing is optional

The accuracy rating does not establish across-wafer uniformity over the full temperature range. SM-150 and HP-150 are separate process stations, including in the Duo cabinet. Review a cooling station separately if controlled cooling is required.

Specifications and independent equipment record

Manufacturer: HP-150 specifications →

Manufacturer: HP-150 soft-bake and hard-bake station →

OST: existing HP-150 equipment listing →

China website: English HP-150 configuration page →

Prepared by the China team; this is not a manufacturer-issued technical datasheet. Institutional listings identify equipment and use, rather than endorsements or standard options for every order. Final scope follows the confirmed configuration.

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